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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/625,109	07/22/2003	Zhiyong Wang	42P16894	9397

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EXAMINER

HAFIZ, MURSALIN B

ART UNIT PAPER NUMBER

2814

DATE MAILED: 05/18/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary

Application No.

10/625,109

Applicant(s)

WANG ET AL.

Examiner

Mursalin B. Hafiz

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-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 21 February 2006.
- 2a) ☒ This action is **FINAL**. 2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1,2,4-9 and 11-14 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 1,2,4-9 and 11-14 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
- Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
- Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some * c) ☐ None of:
- ☐ Certified copies of the priority documents have been received.
 - ☐ Certified copies of the priority documents have been received in Application No. _____.
 - ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
- * See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- 1) ☒ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) ☐ Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date _____
- 4) ☐ Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____
- 5) ☐ Notice of Informal Patent Application (PTO-152)
- 6) ☐ Other: _____

DETAILED ACTION

Response to Amendment

Applicant's amendment filed on February 21, 2006 is hereby acknowledged.

Claims 3 and 10 are cancelled. Claims 1, 4, 5, 8, 11, and 12 are amended.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 1, 5-8, and 12-14 are rejected under 35 U.S.C. 103(a) as being unpatentable over Murayama (EP 0969504 A1) previously applied, in view of Brodsky et al. (US 6,731,012 B1) newly cited.

Regarding claim 1, Murayama discloses in Fig. 6 and 7 an electronic assembly, comprising:

a carrier substrate [10] having an upper plane;

a die having a die substrate [12] and an integrated circuit formed on one side of the die substrate, the die having a lower major surface over the upper plane, an upper major surface, and a plurality of side edge surfaces from the upper major surface to the lower major surface, a corner edge portion where extensions of two of the side edge surfaces meet, having been removed [D]; and

a solidified underfill material [18] between and contacting both the upper plane of the carrier substrate [10] and the lower surface of the die [12].

Murayama does not disclose the die is rounded at the corner edge portion. However, Brodsky et al. disclosed in Fig. 5, an analogous device wherein the die is rounded at the corner edge portion. It would have been obvious to one of ordinary skilled in the art at the time of the invention was made to incorporate Brodsky's teaching into Murayama's device at least to reduce crack propagation originating at the edges of the chip [abstract].

Regarding claim 5, Murayama discloses in Fig. 6 the die is rounded at the corner edge portion, wherein an entire thickness from the upper to the lower major surface is rounded.

Regarding claim 6, inventor discloses in the 'Discussion of Related Art' the underfill material has a different CTE than the substrate [paragraph 0004]. The inventor admits that "underfill material typically has a CTE ... higher than that of the substrate."

Regarding claim 7, Murayama discloses in Fig. 7 a plurality of conductive interconnection members [16] between and electrically connecting the carrier substrate [10] to the die [12], the underfill material [18] being disposed between the conductive interconnection members [16].

Regarding claim 8, Murayama discloses in Fig. 6 and 7 an electronic component, comprising:

a die [12] having a die substrate and an integrated circuit formed on the die substrate, the die having upper and lower major surface a corner edge portion where extensions of two of the side edge surfaces meet, having been removed [D].

Murayama does not disclose the die is rounded at the corner edge portion. However, Brodsky et al. disclosed in Fig. 5, an analogous device wherein the die is rounded at the corner edge portion. It would have been obvious to one of ordinary skill in the art at the time of the invention was made to incorporate Brodsky's teaching into Murayama's device at least to reduce crack propagation originating at the edges of the chip [abstract].

Regarding claim 12, Murayama discloses in Fig. 6 the die is rounded at the corner edge portion, wherein an entire thickness from the upper to the lower major surface is rounded.

Regarding claim 13, inventor discloses in the 'Discussion of Related Art' the underfill material has a different CTE than the substrate [paragraph 0004]. The inventor admits that "underfill material typically has a CTE ... higher than that of the substrate."

Regarding claim 14, Murayama discloses in Fig. 7 a plurality of conductive interconnection members [16] between and electrically connecting the carrier substrate [10] to the die [12], the underfill material [18] being disposed between the conductive interconnection members [16].

Claims 2,4,9, and 11 are rejected under 35 U.S.C. 103(a) as being unpatentable over Murayama (EP 0969504 A1) previously applied, in view of Brodsky et al. (US 6,731,012 B1) newly cited, as applied to claims 1 and 8 above, and further in view of 'Specification' of the application.

Regarding claim 2 and 4, wherein the corner edge portion has an area of between $537\mu\text{m}^2$ and $860000\mu\text{m}^2$ and the die has a radius of between $50\mu\text{m}$ and

1000 μ m at the corner edge portion, the inventor admits that claimed dimensions are not critical by saying "the purpose for providing these ranges is merely to establish that the intent is to differentiate over the tiny radii found on sharp, even knifelike edges." Hence the claimed limitation is merely an optimization. Murayama discloses in Fig. 6 that significant amount of the corner is removed.

Regarding claim 9 and 11, wherein the corner edge portion has an area of between 537 μ m² and 860000 μ m² and the die has a radius of between 50 μ m and 1000 μ m at the corner edge portion, the inventor admits that claimed dimensions are not critical by saying "the purpose for providing these ranges is merely to establish that the intent is to differentiate over the tiny radii found on sharp, even knifelike edges." Hence the claimed limitation is merely an optimization. Murayama discloses in Fig. 6 that significant amount of the corner is removed.

Response to Arguments

Applicant's arguments with respect to claims 1, 2, 4-9, and 11-14 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the

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shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Mursalin B. Hafiz whose telephone number is 571-272-8604. The examiner can normally be reached on m-f 8-5.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy can be reached on 571-272-1705. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

mbh



HOAI PHAM
PRIMARY EXAMINER